

NBXSBA024, NBXSBB024, NBXMBB024

2.5 V / 3.3 V, 622.08 MHz LVPECL Clock Oscillator

The single frequency, crystal oscillator (XO) is designed to meet today's requirements for 2.5 V / 3.3 V LVPECL clock generation applications. The device uses a high Q fundamental crystal and Phase Lock Loop (PLL) multiplier to provide 622.08 MHz, ultra low jitter and phase noise LVPECL differential output.

This device is a member of ON Semiconductor's PureEdge™ clock family that provides accurate and precision clock solutions.

Frequency stability options available as either ± 50 PPM NBXSBA024 (Industrial Temperature Range) or ± 20 PPM NBXSBB024/NBXMBB024 (Commercial Temperature Range).

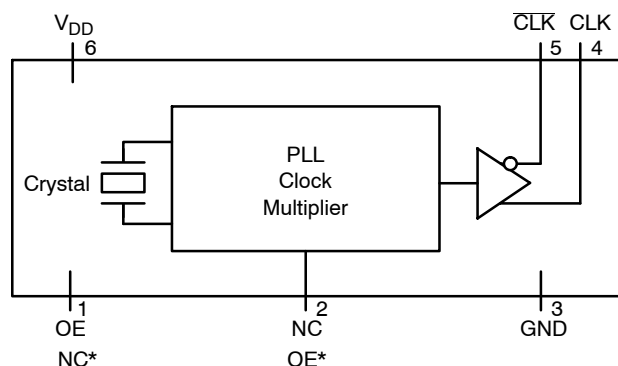
Available in 5 mm x 7 mm SMD (CLCC) package on 16 mm tape and reel in quantities of 1,000 and 100.

Features

- LVPECL Differential Output
- Uses High Q Fundamental Mode Crystal and PLL Multiplier
- Ultra Low Jitter and Phase Noise – 0.5 ps (12 kHz – 20 MHz)
- Output Frequency – 622.08 MHz
- Hermetically Sealed Ceramic SMD Package
- RoHS Compliant
- Operating Range: 2.5 V $\pm 5\%$ or 3.3 V $\pm 10\%$
- Total Frequency Stability – ± 20 PPM; ± 50 PPM
- This is a Pb-Free Device

Applications

- SONET Line Card
- Networking
- Optical Systems



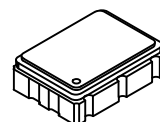
*NBXMBB024 device pintout

Figure 1. Simplified Logic Diagram



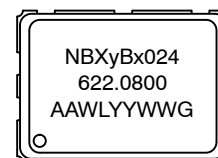
ON Semiconductor®

<http://onsemi.com>



6 PIN CLCC
LN SUFFIX
CASE 848AB

MARKING DIAGRAM



NBXSBA024 = Specific Device Code
x = A or B
y = S or M
NBXSBA024 (± 50 PPM)
NBXSBB024 (± 20 PPM)
622.0800 = Output Frequency (MHz)
AA = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping†
NBXSBA024LN1TAG	CLCC-6 (Pb-Free)	1000/ Tape & Reel
NBXSBB024LN1TAG*	CLCC-6 (Pb-Free)	1000/ Tape & Reel
NBXSBA024LNHTAG	CLCC-6 (Pb-Free)	100/ Tape & Reel
NBXMBB024LN1TAG	CLCC-6 (Pb-Free)	1000/ Tape & Reel
NBXMBB024LNHTAG	CLCC-6 (Pb-Free)	100/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

* Please contact sales office for availability

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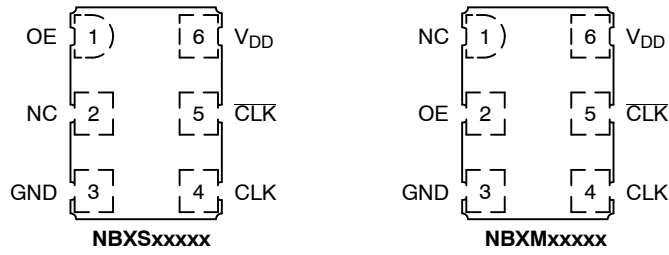


Figure 2. Pin Connections (Top View)

Table 1. PIN DESCRIPTION

Pin No.	Symbol	I/O	Description
1	OE/NC*	LVTTTL/LVCMOS Control Input	Output Enable Pin. When left floating pin defaults to logic HIGH and output is active. See OE pin description Table 2.
2	NC/OE*	N/A	No Connect.
3	GND	Power Supply	Ground 0 V
4	CLK	LVPECL Output	Non-Inverted Clock Output. Typically loaded with 50 Ω receiver termination resistor to $V_{TT} = V_{DD} - 2$ V.
5	$\overline{\text{CLK}}$	LVPECL Output	Inverted Clock Output. Typically loaded with 50 Ω receiver termination resistor to $V_{TT} = V_{DD} - 2$ V.
6	V _{DD}	Power Supply	Positive power supply voltage. Voltage should not exceed 2.5 V $\pm$ 5% or 3.3 V $\pm$ 10%.

*NBXMBA024 device pinout

Table 2. OUTPUT ENABLE TRI-STATE FUNCTION

OE Pin	Output Pins
Open	Active
HIGH Level	Active
LOW Level	High Z

Table 3. ATTRIBUTES

Characteristic	Value
Internal Default State Resistor	170 k Ω
ESD Protection Human Body Model	2 kV
Machine Model	200 V
Meets or Exceeds JEDEC Standard EIA/JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{DD}	Positive Power Supply	GND = 0 V		4.6	V
I _{out}	LVPECL Output Current	Continuous Surge		25 50	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-55 to +120	°C
T _{sol}	Wave Solder	See Figure 5		260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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Table 5. DC CHARACTERISTICS ($V_{DD} = 2.5\text{ V} \pm 5\%$; $3.3\text{ V} \pm 10\%$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) (Note 2)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
I_{DD}	Power Supply Current			95	105	mA
V_{IH}	OE Input HIGH Voltage		2000		V_{DD}	mV
V_{IL}	OE Input LOW Voltage		$GND - 300$		800	mV
I_{IH}	Input HIGH Current	OE	-100		+100	μA
I_{IL}	Input LOW Current	OE	-100		+100	μA
V_{OH}	Output HIGH Voltage		$V_{DD}-1195$		$V_{DD}-945$	mV
V_{OL}	Output LOW Voltage		$V_{DD}-1945$		$V_{DD}-1600$	mV
V_{OUTPP}	Output Voltage Amplitude			700		mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Measurement taken with outputs terminated with $50\ \Omega$ to $V_{DD} - 2.0\text{ V}$. See Figure 4.

Table 6. AC CHARACTERISTICS ($V_{DD} = 2.5\text{ V} \pm 5\%$; $3.3\text{ V} \pm 10\%$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) (Note 3)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
f_{CLKOUT}	Output Clock Frequency			622.08		MHz
Δf	Frequency Stability NBXSBB024, NBXMBB024 NBXSBA024	0°C to $+70^\circ\text{C}$ -40°C to $+85^\circ\text{C}$ (Note 4)			± 20 ± 50	ppm
Φ_{NOISE}	Phase-Noise Performance $f_{CLKout} = 622.08\text{ MHz}$ (See Figure 3)	100 Hz of Carrier		-88		dBc/Hz
		1 kHz of Carrier		-108		dBc/Hz
		10 kHz of Carrier		-115		dBc/Hz
		100 kHz of Carrier		-116		dBc/Hz
		1 MHz of Carrier		-122		dBc/Hz
		10 MHz of Carrier		-149		dBc/Hz
$t_{jit}(\Phi)$	RMS Phase Jitter	12 kHz to 20 MHz		0.5	0.7	ps
t_{jitter}	Cycle to Cycle, RMS	1000 Cycles		1.5	8	ps
	Cycle to Cycle, Peak-to-Peak	1000 Cycles		15	30	ps
	Period, RMS	10,000 Cycles		1	4	ps
	Period, Peak-to-Peak	10,000 Cycles		10	20	ps
$t_{OE/OD}$	Output Enable/Disable Time				200	ns
t_{DUTY_CYCLE}	Output Clock Duty Cycle (Measured at Cross Point)		45	50	55	%
t_R	Output Rise Time (20% and 80%)			250	400	ps
t_F	Output Fall Time (80% and 20%)			250	400	ps
t_{start}	Start-up Time			1	5	ms
	Aging	1 st Year			3	ppm
		Every Year After 1 st			1	ppm

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Measurement taken with outputs terminated with $50\ \Omega$ to $V_{DD} - 2.0\text{ V}$. See Figure 4.

4. Parameter guarantee 10 years aging. Includes initial stability at 25°C , shock, vibration, and first year aging.

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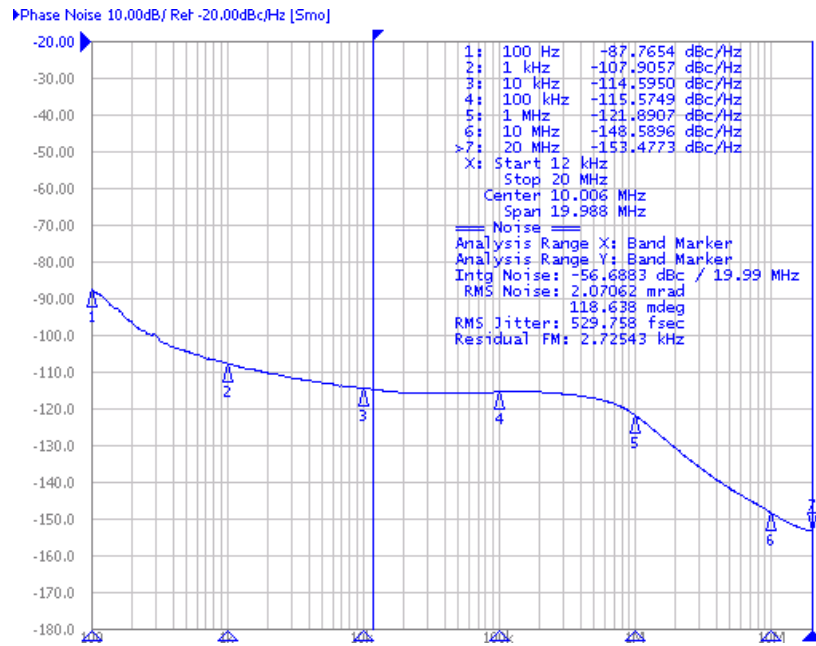


Figure 3. Typical Phase Noise Plot

Table 7. RELIABILITY COMPLIANCE

Parameter	Standard	Method
Shock	Mechanical	MIL-STD-833, Method 2002, Condition B
Solderability	Mechanical	MIL-STD-833, Method 2003
Vibration	Mechanical	MIL-STD-833, Method 2007, Condition A
Solvent Resistance	Mechanical	MIL-STD-202, Method 215
Thermal Shock	Environment	MIL-STD-833, Method 1011, Condition A
Moisture Level Sensitivity	Environment	MSL1 260°C per IPC/JEDEC J-STD-020D

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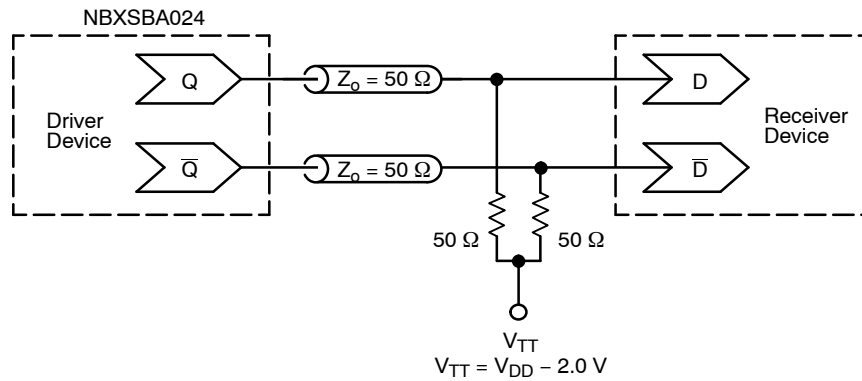


Figure 4. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

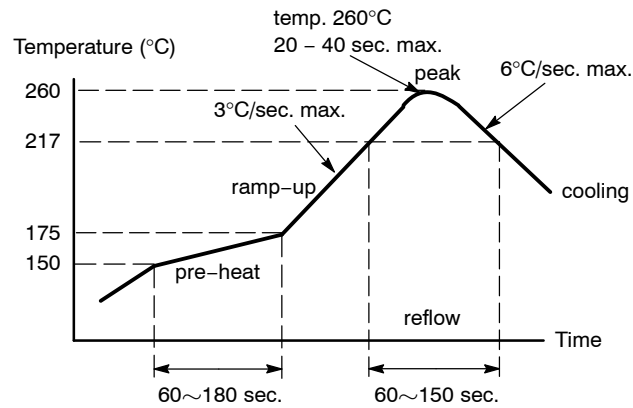


Figure 5. Recommended Reflow Soldering Profile

